MC74HC132A

Quad 2-Input NAND Gate with Schmitt-Trigger Inputs

High–Performance Silicon–Gate CMOS

The MC74HC132A is identical in pinout to the LS132. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

The HC132A can be used to enhance noise immunity or to square up slowly changing waveforms.

- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2.0 to 6.0 V
- Low Input Current: 1.0 μA
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the Requirements Defined by JEDEC Standard No. 7A
- Chip Complexity: 72 FETs or 18 Equivalent Gates

LOGIC DIAGRAM

A1 1, B1 2 → 3 Y1
A2 4, B2 5 → 6 Y2
A3 9, B3 10 → 8 Y3
A4 12, B4 13 → 11 Y4

$Y = \overline{AB}$

PIN 14 = V_{CC}
PIN 7 = GND

FUNCTION TABLE

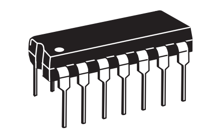
Inputs		Output
A	B	Y
L	L	H
L	H	H
H	L	H
H	H	L



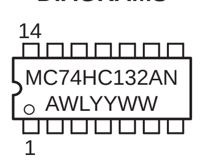
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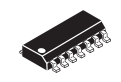
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MARKING DIAGRAMS

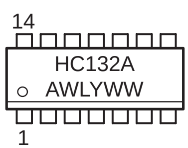


PDIP–14
N SUFFIX
CASE 646





SOIC–14
D SUFFIX
CASE 751A



A = Assembly Location
WL or L = Wafer Lot
YY or Y = Year
WW or W = Work Week

PIN ASSIGNMENT

A1	1	14	V_{CC}
B1	2	13	B4
Y1	3	12	A4
A2	4	11	Y4
B2	5	10	B3
Y2	6	9	A3
GND	7	8	Y3

ORDERING INFORMATION

Device	Package	Shipping
MC74HC132AN	PDIP–14	2000 / Box
MC74HC132AD	SOIC–14	55 / Rail
MC74HC132ADR2	SOIC–14	2500 / Reel

March, 2000 – Rev. 7
Publication Order Number:
MC74HC132A/D

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	– 0.5 to + 7.0	V
V_{in}	DC Input Voltage (Referenced to GND)	– 1.5 to V_{CC} + 1.5	V
V_{out}	DC Output Voltage (Referenced to GND)	– 0.5 to V_{CC} + 0.5	V
I_{in}	DC Input Current, per Pin	± 20	mA
I_{out}	DC Output Current, per Pin	± 25	mA
I_{CC}	DC Supply Current, V_{CC} and GND Pins	± 50	mA
P_D	Power Dissipation in Still Air, Plastic DIP† SOIC Package†	750 500	mW
T_{stg}	Storage Temperature	– 65 to + 150	°C
T_L	Lead Temperature, 1 mm from Case for 10 Seconds (Plastic DIP or SOIC Package)	260	°C

*Maximum Ratings are those values beyond which damage to the device may occur.
Functional operation should be restricted to the Recommended Operating Conditions.
†Derating — Plastic DIP: – 10 mW/°C from 65° to 125°C
SOIC Package: – 7 mW/°C from 65° to 125°C
For high frequency or heavy load considerations, see Chapter 2 of the ON Semiconductor High–Speed CMOS Data Book (DL129/D).

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range GND ≤ (V_{in} or V_{out}) ≤ V_{CC}.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	2.0	6.0	V
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Referenced to GND)	0	V_{CC}	V
T_A	Operating Temperature, All Package Types	– 55	+ 125	°C
t_r, t_f	Input Rise and Fall Time (Figure 1)	—	no limit*	ns

*When V_{in} ~ 0.5 V_{CC}, I_{CC} >> quiescent current.

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

Symbol	Parameter	Test Conditions	V_{CC} V	Guaranteed Limit 25°C	Guaranteed Limit – 40°C to + 85°C	Guaranteed Limit – 55°C to + 125°C	Unit
V_{T+} max	Maximum Positive–Going Input Threshold Voltage (Figure 3)	V_{out} = 0.1 V $\|I_{out}\|$ ≤ 20 µA	2.0 4.5 6.0	1.5 3.15 4.2	1.5 3.15 4.2	1.5 3.15 4.2	V
V_{T+} min	Minimum Positive–Going Input Threshold Voltage (Figure 3)	V_{out} = 0.1 V $\|I_{out}\|$ ≤ 20 µA	2.0 4.5 6.0	1.0 2.3 3.0	0.95 2.25 2.95	0.95 2.25 2.95	V
V_{T-} max	Maximum Negative–Going Input Threshold Voltage (Figure 3)	V_{out} = V_{CC} – 0.1 V $\|I_{out}\|$ ≤ 20 µA	2.0 4.5 6.0	0.9 2.0 2.6	0.95 2.05 2.65	0.95 2.05 2.65	V
V_{T-} min	Minimum Negative–Going Input Threshold Voltage (Figure 3)	V_{out} = V_{CC} – 0.1 V $\|I_{out}\|$ ≤ 20 µA	2.0 4.5 6.0	0.3 0.9 1.2	0.3 0.9 1.2	0.3 0.9 1.2	V
$V_H$max Note 2	Maximum Hysteresis Voltage (Figure 3)	V_{out} = 0.1 V or V_{CC} – 0.1 V $\|I_{out}\|$ ≤ 20 µA	2.0 4.5 6.0	1.2 2.25 3.0	1.2 2.25 3.0	1.2 2.25 3.0	V
$V_H$min Note 2	Minimum Hysteresis Voltage (Figure 3)	V_{out} = 0.1 V or V_{CC} – 0.1 V $\|I_{out}\|$ ≤ 20 µA	2.0 4.5 6.0	0.2 0.4 0.5	0.2 0.4 0.5	0.2 0.4 0.5	V

NOTE: 1. $V_H$min > (V_{T+} min) – (V_{T-} max); $V_H$max = (V_{T+} max) + (V_{T-} min).
NOTE: Information on typical parametric values can be found in Chapter 2 of the ON Semiconductor High–Speed CMOS Data Book (DL129/D).

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

Symbol	Parameter	Test Conditions	V_{CC} V	Guaranteed Limit – 55 to 25°C	Guaranteed Limit ≤ 85°C	Guaranteed Limit ≤ 125°C	Unit
V_{OH}	Minimum High–Level Output Voltage	$V_{in} \le V_{T-}$ min or V_{T+} max $\lvert I_{out} \rvert \le 20\ \mu A$	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V
		$V_{in} \le -V_{T-}$ min or V_{T+} max $\lvert I_{out} \rvert \le 4.0$ mA $\lvert I_{out} \rvert \le 5.2$ mA	4.5 6.0	3.98 5.48	3.84 5.34	3.7 5.2	
V_{OL}	Maximum Low–Level Output Voltage	$V_{in} \ge V_{T+}$ max $\lvert I_{out} \rvert \le 20\ \mu A$	2.0 4.5 6.0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V
		$V_{in} \ge V_{T+}$ max $\lvert I_{out} \rvert \le 4.0$ mA $\lvert I_{out} \rvert \le 5.2$ mA	4.5 6.0	0.26 0.26	0.33 0.33	0.4 0.4	
I_{in}	Maximum Input Leakage Current	$V_{in} = V_{CC}$ or GND	6.0	± 0.1	± 1.0	± 1.0	µA
I_{CC}	Maximum Quiescent Supply Current (per Package)	$V_{in} = V_{CC}$ or GND $I_{out} = 0\ \mu A$	6.0	1.0	10	40	µA

AC ELECTRICAL CHARACTERISTICS (C_L = 50 pF, Input $t_r = t_f$ = 6.0 ns)

Symbol	Parameter	V_{CC} V	Guaranteed Limit – 55 to 25°C	Guaranteed Limit ≤ 85°C	Guaranteed Limit ≤ 125°C	Unit
t_{PLH}, t_{PHL}	Maximum Propagation Delay, Input A or B to Output Y (Figures 1 and 2)	2.0 4.5 6.0	125 25 21	155 31 26	190 38 32	ns
t_{TLH}, t_{THL}	Maximum Output Transition Time, Any Output (Figures 1 and 2)	2.0 4.5 6.0	75 15 13	95 19 16	110 22 19	ns
C_{in}	Maximum Input Capacitance	—	10	10	10	pF

NOTE: For propagation delays with loads other than 50 pF, and information on typical parametric values, see Chapter 2 of the ON Semiconductor High–Speed CMOS Data Book (DL129/D).

		Typical @ 25°C, V_{CC} = 5.0 V	
C_{PD}	Power Dissipation Capacitance (Per Gate)*	24	pF

* Used to determine the no–load dynamic power consumption: $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$. For load considerations, see Chapter 2 of the ON Semiconductor High–Speed CMOS Data Book (DL129/D).

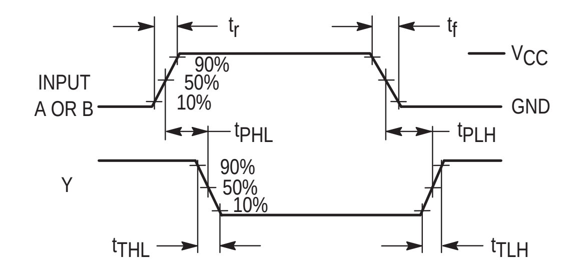
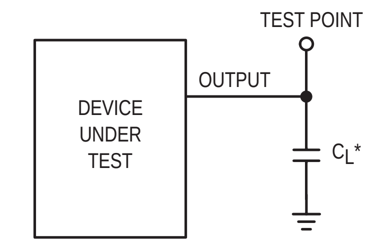


Figure 1. Switching Waveforms



*Includes all probe and jig capacitance

Figure 2. Test Circuit

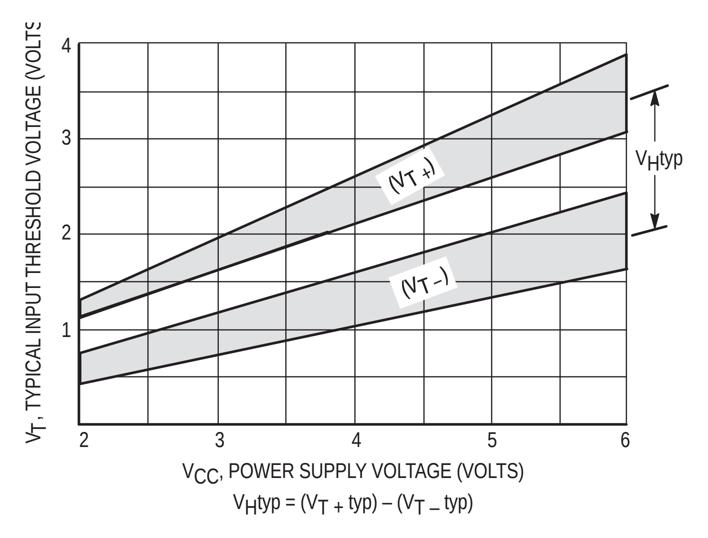
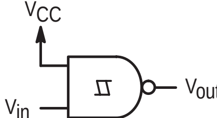


Figure 3. Typical Input Threshold, V_{T+}, V_{T-} Versus Power Supply Voltage



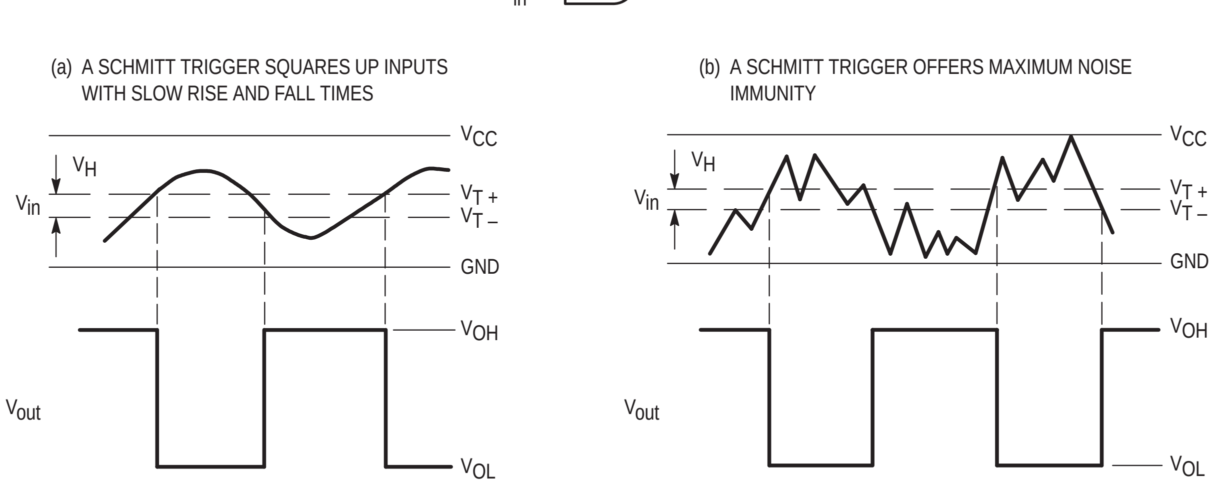
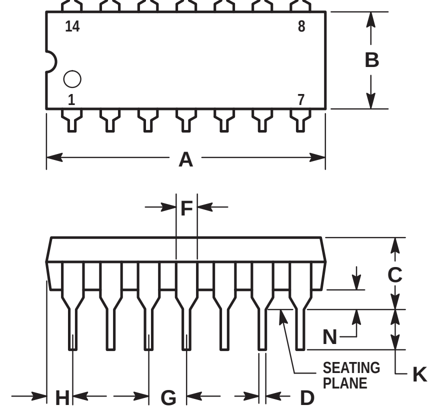
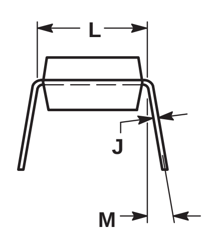


Figure 4. Typical Schmitt–Trigger Applications

PACKAGE DIMENSIONS

PDIP–14
N SUFFIX
CASE 646–06
ISSUE L

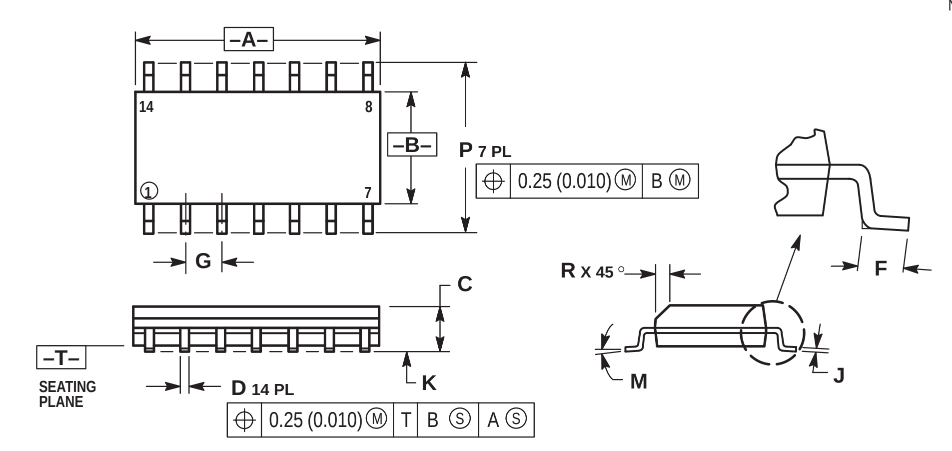




NOTES:
1. LEADS WITHIN 0.13 (0.005) RADIUS OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION.
2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
3. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
4. ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.715	0.770	18.16	19.56
B	0.240	0.260	6.10	6.60
C	0.145	0.185	3.69	4.69
D	0.015	0.021	0.38	0.53
F	0.040	0.070	1.02	1.78
G	0.100 BSC		2.54 BSC	
H	0.052	0.095	1.32	2.41
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.300 BSC		7.62 BSC	
M	0°	10°	0°	10°
N	0.015	0.039	0.39	1.01

SOIC–14
D SUFFIX
CASE 751A–03
ISSUE F



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	8.55	8.75	0.337	0.344
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

Notes

Notes

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